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Making semiconductor chip thin independently of wafer size - by cutting protective plate to same size as chip after wafer is made thin, to increase workability of chip NoAbstract
Patent Assignee: SONY CORP

Patent Family

Patent Number	Kind	Date	Application Number	Kind	Date	Week	Type
JP 5055278	A	19930305	JP 91211207	A	19910823	199314	B

Priority Applications (Number Kind Date): JP 91211207 A (19910823)

Patent Details

Patent	Kind	Language	Page	Main IPC	Filing Notes
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**SEMICONDUCTOR DEVICE****Publication Number:** 05-055278 (JP 5055278 A) , March 05, 1993**Inventors:**

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Application Number: 03-211207 (JP 91211207) , August 23, 1991**International Class (IPC Edition 5):**

- H01L-021/56
- H01L-021/304
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- H01L-023/12
- H01L-023/28

JAPIO Class:

- 42.2 (ELECTRONICS--- Solid State Components)

Abstract:

PURPOSE: To improve handling operability of a semiconductor chip in a manufacturing step while reducing in thickness of the chip itself irrespective of the size of a semiconductor wafer and to obtain a small-sized thin semiconductor device.

CONSTITUTION: A semiconductor wafer 1 is reduced in thickness while forming a resin film 3 in a protective reinforcing plate, protrusion electrodes 5 protrude from the film 3 on a semiconductor chip 2 as an external connection terminal, and the film 3 is so cut as to be the same in size as the chip 2. Thus, a semiconductor device having high reliability, easy handling, small size and thickness, is obtained. (From: *Patent Abstracts of Japan*, Section: E, Section No. 1394, Vol. 17, No. 356, Pg. 5, July 06, 1993)

JAPIO

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